

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT								
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Byung Tai Do</td> <td>06/20/2007</td> </tr> <tr> <td>Heap Hoe Kuan</td> <td>06/20/2007</td> </tr> <tr> <td>Seng Guan Chow</td> <td>06/20/2007</td> </tr> </tbody> </table>		Name	Execution Date	Byung Tai Do	06/20/2007	Heap Hoe Kuan	06/20/2007	Seng Guan Chow	06/20/2007
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Byung Tai Do	06/20/2007								
Heap Hoe Kuan	06/20/2007								
Seng Guan Chow	06/20/2007								
<b>RECEIVING PARTY DATA</b>									
<b>Name:</b>	STATS ChipPAC, Ltd.								
<b>Street Address:</b>	5 Yishun Street 23								
<b>City:</b>	Singapore								
<b>State/Country:</b>	SINGAPORE								
<b>Postal Code:</b>	768442								
<b>PROPERTY NUMBERS Total: 1</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11768825</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11768825				
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Application Number:	11768825								
<b>CORRESPONDENCE DATA</b>									
<b>Fax Number:</b>	(602)229-5690								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
<b>Phone:</b>	602-229-5290								
<b>Email:</b>	moneill@quarles.com								
<b>Correspondent Name:</b>	Robert D. Atkins								
<b>Address Line 1:</b>	QUARLES & BRADY LLP								
<b>Address Line 2:</b>	Two North Central Avenue								
<b>Address Line 4:</b>	Phoenix, ARIZONA 85004								
<b>ATTORNEY DOCKET NUMBER:</b>	125155.00022								
<b>NAME OF SUBMITTER:</b>	Robert D. Atkins								

Total Attachments: 3  
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ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled PACKAGE-IN-PACKAGE USING THROUGH-HOLE VIA DIE ON SAW STREETS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00022, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for BYUNG TAI DO

Witnessed on this date:

20 Jun 2007

Signature of Witness:



Printed Name of Witness:

CHUA FEI EE

Address of Witness:

10 Ang Mo Kio St 65  
Techpoint #05-17/20  
Singapore 569059

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEAP HOE KUAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled PACKAGE-IN-PACKAGE USING THROUGH-HOLE VIA DIE ON SAW STREETS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00022, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for HEAP HOE KUAN

Witnessed on this date: 20 June 2007

Signature of Witness: 

Printed Name of Witness: HUANG RUI

Address of Witness: 10 Ang Mo Kio St 65  
Tech Point #05-17/20  
Singapore 569659.

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SENG GUAN CHOW of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled PACKAGE-IN-PACKAGE USING THROUGH-HOLE VIA DIE ON SAW STREETS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00022, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

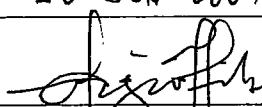
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\_\_\_\_\_  
Signature for SENG GUAN CHOW

Witnessed on this date: 26 JUN 2007  
Signature of Witness:   
Printed Name of Witness: DIOSCORO A. MERILO  
Address of Witness: 10 ANG MO KIO ST. 65  
TECHPOINT # 05-17/20  
SINGAPORE 569059

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